



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20140605000**  
**Qualification of TI Clark and NSE as Additional Assembly**  
**and Test Site for Select Devices**  
**Change Notification / Sample Request**

**Date:** 6/13/2014  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services  
Phone: +1(214) 480-6037  
Fax: +1(214) 480-6659

**20140605000**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
PCM3070IRHBT	null
TLV320AIC3204IRHBR	null
TLV320AIC3204IRHBT	null
TPS51206DSQR	null
TPS51206DSQT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20140605000			<b>PCN Date:</b>	06/13/2014
<b>Title:</b>	Qualification of TI Clark and NSE as Additional Assembly and Test Site for Select Devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	09/13/2014	<b>Estimated Sample Availability:</b>	Date Provided at Sample request		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
<p>Texas Instruments Incorporated is announcing the qualification of TI Clark and NSE as additional assembly/test site for select devices listed in the "Product Affected" Section. Current assembly sites are as follows and no material differences between assembly sites.</p> <ul style="list-style-type: none"> <li>• <b>Group 1 Device: TI Malaysia to TI Clark</b></li> <li>• <b>Group 2 Device: TI Clark to NSE</b></li> </ul> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					
<b>Reason for Change:</b>					
Continuity of supply.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					

**Changes to product identification resulting from this PCN:****Group 1 Device: TI Malaysia to TI Clark**

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Clark	Assembly Site Origin (22L)	ASO: QAB

ASSEMBLY SITE CODES: TI Malaysia = K , TI-Clark = I

**Group 2 Device: TI Clark to NSE**

Assembly Site		
TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB
NSE Thailand	Assembly Site Origin (22L)	ASO: NSE

ASSEMBLY SITE CODES: TI CLARK = I, NSE = J

Sample product shipping label (not actual product label)

**Product Affected: Group 1 Device (TI Malaysia to TI Clark)**

TPS51206DSQR	TPS51206DSQR-P	TPS51206DSQT
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**Product Affected: Group 2 Device (TI Clark to NSE)**

PCM3070IRHBR	PCM3070IRHBT	TLV320AIC3204IRHBR	TLV320AIC3204IRHBT
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**Qualification Data : Group 1**

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

**Qual Vehicle : TPS51206DSQ (MSL2-260C)****Package Construction Details**

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	10-DSQ, WSON	Mount Compound:	4207768
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

**Qualification:** ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size/Fail
Manufacturability	(per mfg. Site specification)	Pass

## Reference Qualification Data

Qual Vehicle : TPS51518RUKR (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	20-RUK, WQFN	Mount Compound:	4207768	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	30/0	-	-
**Life Test	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**High-Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
Manufacturability	(per mfg. Site specification)	Pass	-	-
Notes    ** - Preconditioning sequence: Level 2-260C.				

## Qualification Data : Group 2

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : SN0509043RGC (MSL3-260C)				
Package Construction Details				
Assembly Site:	NSE	Mold Compound:	CZ0134	
# Pins-Designator, Family:	64-RGC, VQFN	Mount Compound:	PZ0031	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	2.0 Mil Dia., Au	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	Pass	Pass	Pass
**Life Test	140C (480 Hrs)	113/0	116/0	116/0
**HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 15 PSIG, 29.7 PSIA (96 Hrs)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (1000 Cyc)	77/0	77/0	77/0
**High-Temp Storage	170C (420 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Solderability	8 Hrs Steam Age	22/0	22/0	22/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	(top side only)	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes    ** - Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>